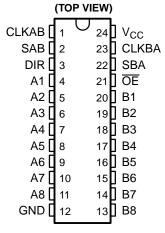
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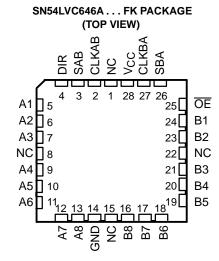
FEATURES

- Operate From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 7.4 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 at V_{CC} = 3.3 V, T_Δ = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})

SN54LVC646A . . . JT OR W PACKAGE SN74LVC646A . . . DB, DW, NS, OR PW PACKAGE



- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



NC - No internal connection

DESCRIPTION/ORDERING INFORMATION

The SN54LVC646A octal bus transceiver and register is designed for 2.7-V to 3.6-V V_{CC} operation, and the SN74LVC646A octal bus transceiver and register is designed for 1.65-V to 3.6-V V_{CC} operation.

ORDERING INFORMATION

T _A	PACKA	AGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC - DW	Tube of 25	SN74LVC646ADW	LVC646A
	30IC - DW	Reel of 2000	SN74LVC646ADWR	LVC646A
	SOP - NS	Reel of 2000	SN74LVC646ANSR	LVC646A
-40°C to 85°C	SSOP - DB	Reel of 2000	SN74LVC646ADBR	LC646A
		Tube of 60	SN74LVC646APW	
	TSSOP - PW	Reel of 2000	SN74LVC646APWR	LC646A
		Reel of 250	SN74LVC646APWT	
	CDIP – JT	Tube of 15	SNJ54LVC646AJT	SNJ54LVC646AJT
–55°C to 125°C	CFP – W	Tube of 85	SNJ54LVC646AW	SNJ54LVC646AW
	LCCC – FK	Tube of 42	SNJ54LVC646AFK	SNJ54LVC646AFK

(1) Package drawings, standard packing quantities, thermal data, symboliztion, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SN54LVC646A, SN74LVC646A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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DESCRIPTION/ORDERING INFORMATION (CONTINUED)

These devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that are performed with the 'LVC646A devices.

Output-enable (\overline{OE}) and direction-control (DIR) inputs control the transceiver functions. In the transceiver mode, data present at the high-impedance port is stored in either register or in both.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. DIR determines which bus receives data when \overline{OE} is low. In the isolation mode (\overline{OE} high), A data is stored in one register and B data can be stored in the other register.

When an output function is disabled, the input function still is enabled and can be used to store and transmit data. Only one of the two buses, A or B, can be driven at a time.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE

		INP	UTS			DAT	A I/O	OPERATION OR
ŌĒ	DIR	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	FUNCTION
Х	Х	↑	Х	Х	Х	Input	Unspecified ⁽¹⁾	Store A, B unspecified ⁽¹⁾
X	X	Χ	\uparrow	X	X	Unspecified ⁽¹⁾	Input	Store B, A unspecified ⁽¹⁾
Н	Х	\uparrow	1	Χ	Χ	Input	Input	Store and B data
Н	Χ	H or L	H or L	Χ	X	Input disabled	Input disabled	Isolation, hold storage
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	X	Н	Output	Input	Stored B data to A bus
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
L	Н	H or L	Χ	Н	Х	Input	Output	Stored A data to B bus

⁽¹⁾ The data-output functions can be enabled or disabled by various signals at $\overline{\text{OE}}$ and DIR. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



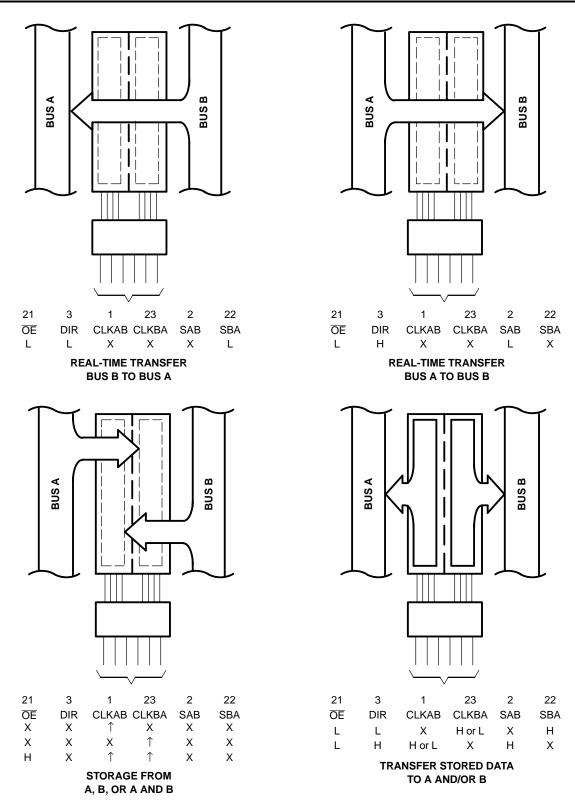
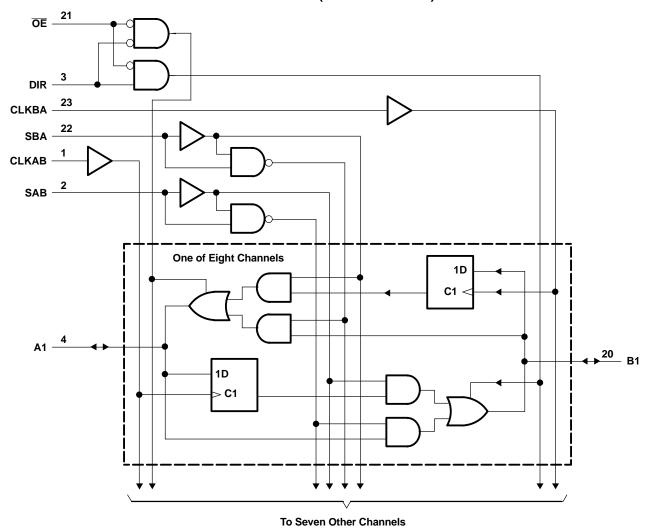


Figure 1. Bus-Management Functions



LOGIC DIAGRAM (POSITIVE LOGIC)



Pin numbers shown are for the DB, DW, JT, NS, PW, and W packages.



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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	6.5	V
VI	Input voltage range ⁽²⁾		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-impe	edance or power-off state(2)	-0.5	6.5	V
Vo	Voltage range applied to any output in the high or love	-0.5	V _{CC} + 0.5	V	
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through V _{CC} or GND			±100	mA
		DB package		63	
0	Daglage thermal impedance (4)	DW package		46	°C/W
θ_{JA}	Package thermal impedance ⁽⁴⁾	NS package		65	·C/VV
		PW package		88	
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions⁽¹⁾

			SN54LVC	646A	SN74LV	C646A	
			MIN	MAX	MIN	MAX	UNIT
	O	Operating	2	3.6	1.65	3.6	
V_{CC}	Supply voltage	Data retention only	1.5		1.5		V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$			$0.65 \times V_{CC}$		
V_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$			1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		2		
		V _{CC} = 1.65 V to 1.95 V				$0.35 \times V_{CC}$	
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$				0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		0.8	
VI	Input voltage	·	0	5.5		5.5	V
\/	Output voltage	High or low state	0	V _{CC}		V _{CC}	V
V _O	Output voltage	3-state	0	5.5		5.5	V
		V _{CC} = 1.65 V				-4	
	Lligh lovel cutout current	V _{CC} = 2.3 V				-8	mA
I _{OH}	High-level output current	$V_{CC} = 2.7 \text{ V}$		-12		-12	ША
		$V_{CC} = 3 V$		-24		-24	
		V _{CC} = 1.65 V				4	
	Love lovel output ourrent	V _{CC} = 2.3 V				8	A
I _{OL}	Low-level output current	V _{CC} = 2.7 V		12		12	mA
		V _{CC} = 3 V		24		24	
Δt/Δν	Input transition rise or fall rate			10		10	ns/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

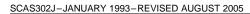
All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

⁽²⁾ The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ The value of V_{CC} is provided in the recommended operating conditions table.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.

SN54LVC646A, SN74LVC646A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS





Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

DAF	AMETER	TEST CONDITI	ONC	V	SN54I	LVC646A		SN74I	VC646A		UNIT
PAR	RAMETER	TEST CONDITI	ONS	V _{cc}	MIN	TYP ⁽¹⁾	MAX	MIN	TYP ⁽¹⁾	MAX	UNII
		1 400 4		1.65 V to 3.6 V				V _{CC} - 0.2			
		$I_{OH} = -100 \mu A$		2.7 V to 3.6 V	V _{CC} - 0.2						
		$I_{OH} = -4 \text{ mA}$		1.65 V				1.2			
V_{OH}		$I_{OH} = -8 \text{ mA}$		2.3 V				1.7			V
		10		2.7 V	2.2			2.2			
		$I_{OH} = -12 \text{ mA}$		3 V	2.4			2.4			
		$I_{OH} = -24 \text{ mA}$		3 V	2.2			2.2			
		1 400 1		1.65 V to 3.6 V						0.2	
		$I_{OL} = 100 \mu A$		2.7 V to 3.6 V			0.2				
.,		I _{OL} = 4 mA		1.65 V						0.45	V
V_{OL}		I _{OL} = 8 mA		2.3 V						0.7	V
		I _{OL} = 12 mA		2.7 V			0.4			0.4	
		I _{OL} = 24 mA		3 V			0.55			0.55	
I _I	Control inputs	V _I = 0 to 5.5 V		3.6 V			±5			±5	μА
I _{off}		V_1 or $V_0 = 5.5 \text{ V}$		0						±10	μΑ
I _{OZ} ⁽²⁾		$V_0 = 0 \text{ to } 5.5 \text{ V}$		3.6 V			±15			±10	μΑ
		$V_I = V_{CC}$ or GND		0.01/			10			10	^
I _{CC}		$3.6 \text{ V} \le V_1 \le 5.5 \text{ V}^{(3)}$	$I_O = 0$	3.6 V			10			10	μΑ
ΔI_{CC}		One input at V _{CC} – 0.6 Other inputs at V _{CC} or		2.7 V to 3.6 V			500			500	μΑ
C _i	Control inputs	V _I = V _{CC} or GND		3.3 V		4.5			4.5		pF
C _{io}	A or B port	$V_O = V_{CC}$ or GND		3.3 V		7.5			7.5		pF

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

			SN54LV	'C646A		
		V _{CC} = 2	V _{CC} = 2.7 V		V_{CC} = 3.3 V \pm 0.3 V	
		MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency		150		150	MHz
t _w	Pulse duration	3.3		3.3		ns
t _{su}	Setup time, data before CLK↑	1.6		1.5		ns
t _h	Hold time, data after CLK↑	1.7		1.7		ns

All typical values are at $V_{CC}=3.3~V,\,T_A=25^{\circ}C.$ For I/O ports, the parameter I_{OZ} includes the input leakage current. This applies in the disabled state only.



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Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

		SN74LVC646A								
		V _{CC} = 1.8 V ± 0.18 V		V_{CC} = 2.5 V \pm 0.2 V		V _{CC} = 2.7 V		V_{CC} = 3.3 V \pm 0.3 V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency		(1)		(1)		150		150	MHz
t_{w}	Pulse duration	(1)		(1)		3.3		3.3		ns
t_{su}	Setup time, data before CLK↑	(1)		(1)		1.6		1.5		ns
t_h	Hold time, data after CLK↑	(1)		(1)		1.7		1.7		ns

⁽¹⁾ This information was not available at the time of publication.

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 2	2.7 V	V_{CC} = 3.3 V \pm 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
f _{max}			150		150		MHz
	A or B	B or A		7.9	1	7.4	
t _{pd}	CLK	A or D		8.8	1	8.4	ns
	SBA or SAB	A or B		9.9	1	8.6	
t _{en}	ŌĒ	A		10.2	1	8.2	ns
t _{dis}	ŌĒ	A		8.9	1	7.5	ns
t _{en}	DIR	В		10.4	1	8.3	ns
t _{dis}	DIR	В		8.7	1	7.9	ns

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

				SN74LVC646A							
PARAMETER	FROM (INPUT)	TO (OUTPUT)		V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		2.7 V	V_{CC} = 3.3 V \pm 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}			(1)		(1)		150		150		MHz
	A or B	B or A	(1)	(1)	(1)	(1)		7.9	1	7.4	
t _{pd}	CLK	A or D	(1)	(1)	(1)	(1)		8.8	1	8.4	ns
	SBA or SAB	A or B	(1)	(1)	(1)	(1)		9.9	1	8.6	
t _{en}	ŌĒ	А	(1)	(1)	(1)	(1)		10.2	1	8.2	ns
t _{dis}	ŌĒ	Α	(1)	(1)	(1)	(1)		8.9	1	7.5	ns
t _{en}	DIR	В	(1)	(1)	(1)	(1)		10.4	1	8.3	ns
t _{dis}	DIR	В	(1)	(1)	(1)	(1)		8.7	1	7.9	ns

⁽¹⁾ This information was not available at the time of publication.

SN54LVC646A, SN74LVC646A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS



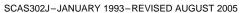


Operating Characteristics

 $T_A = 25^{\circ}C$

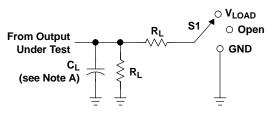
PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT	
Cpd	Power dissipation capacitance	Outputs enabled	f = 10 MHz	(1)	(1)	75	Pα
Сри	per transceiver	Outputs disabled	I = IO WINZ	(1)	(1)	9	рг

⁽¹⁾ This information was not available at the time of publication.





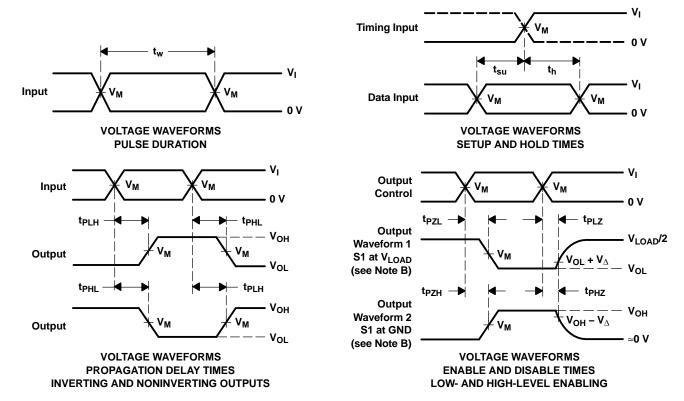
PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

v	INPUTS		.,	V	•		.,
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	R _L	V_{Δ}
1.8 V ± 0.15 V	v _{cc}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.
- H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms





14-Feb-2021

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC646ADBR	ACTIVE	SSOP	DB	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC646A	Samples
SN74LVC646ADW	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC646A	Samples
SN74LVC646ADWG4	ACTIVE	SOIC	DW	24	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC646A	Samples
SN74LVC646APW	ACTIVE	TSSOP	PW	24	60	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC646A	Samples
SN74LVC646APWR	ACTIVE	TSSOP	PW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC646A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

14-Feb-2021

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LVC646A, SN74LVC646A:

Catalog: SN74LVC646A

Military: SN54LVC646A

Space: SN54LVC646A-SP

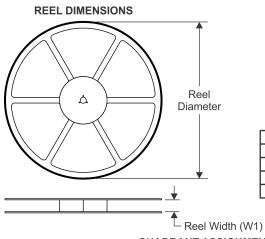
NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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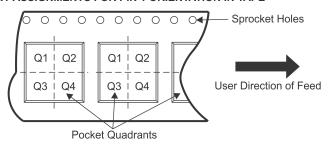
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC646ADBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74LVC646APWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

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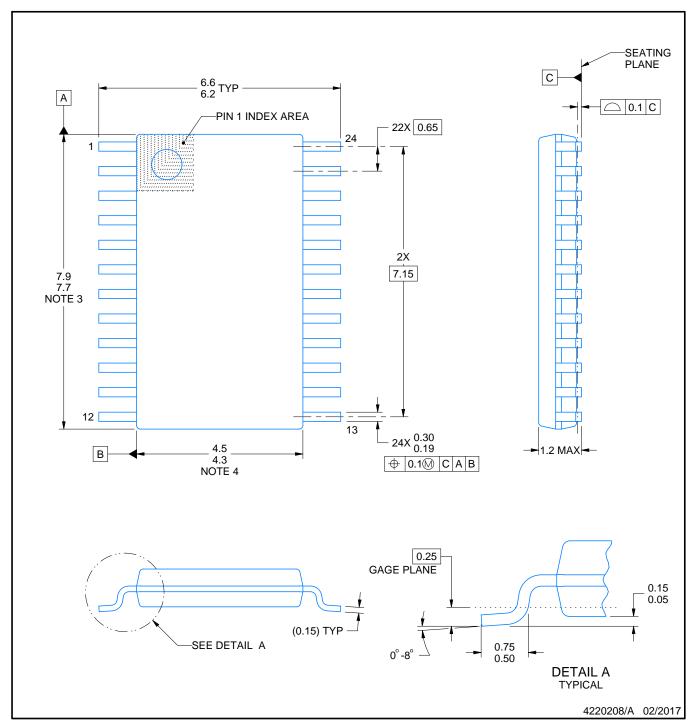


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC646ADBR	SSOP	DB	24	2000	853.0	449.0	35.0
SN74LVC646APWR	TSSOP	PW	24	2000	853.0	449.0	35.0



SMALL OUTLINE PACKAGE



NOTES:

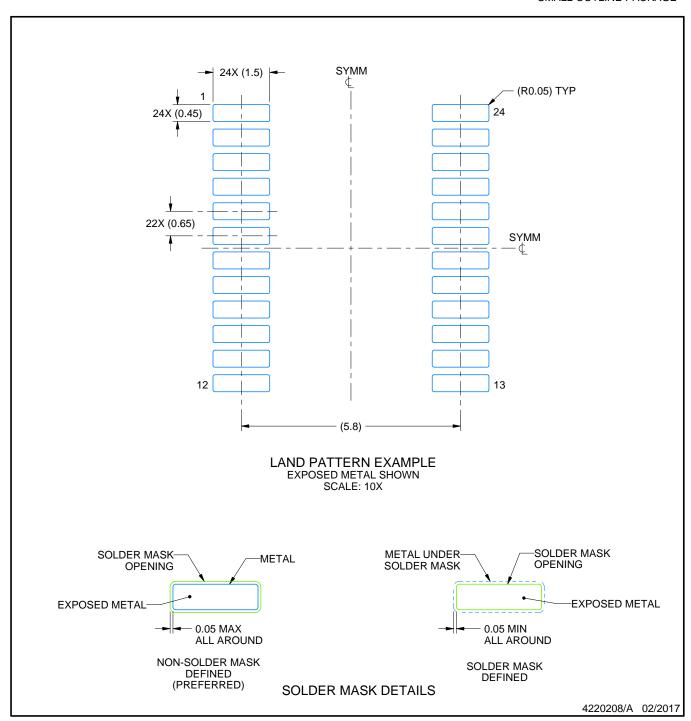
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



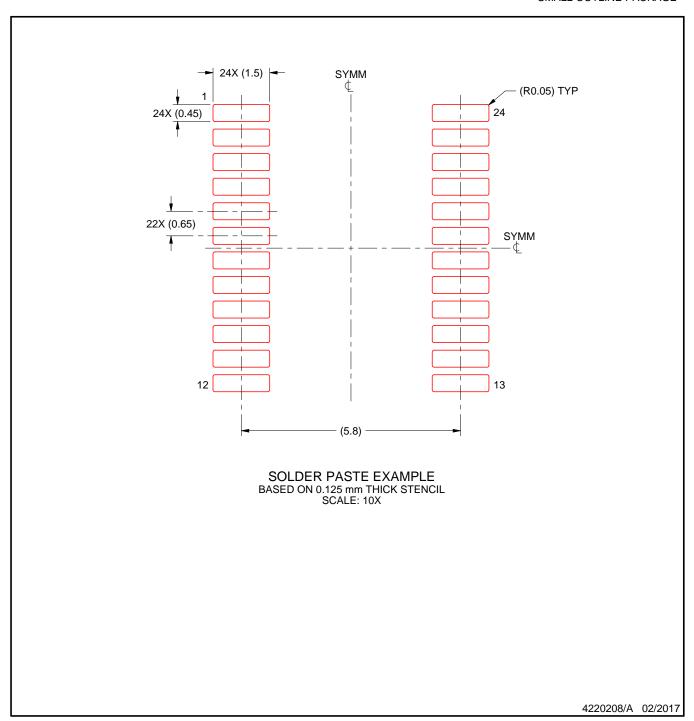
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



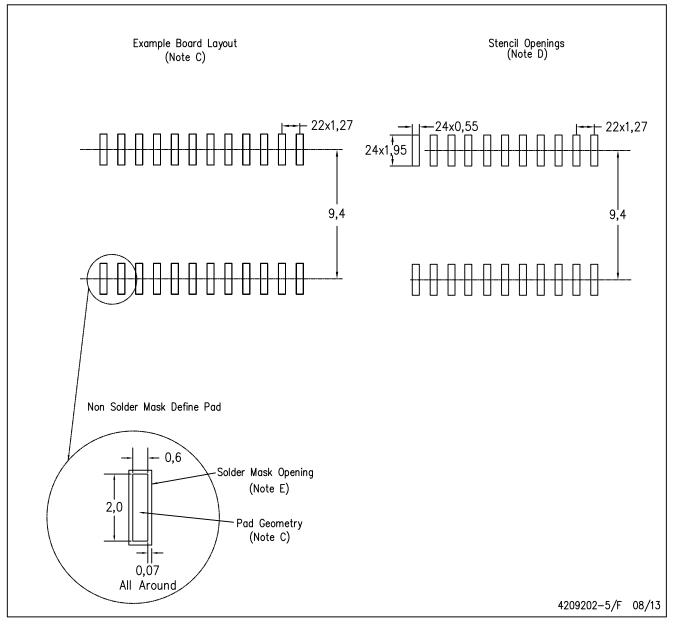
NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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